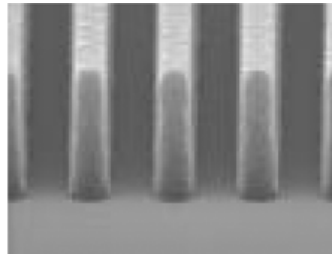


News from our Product Range ...

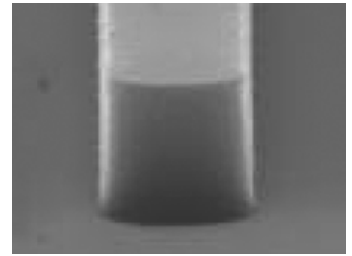
AZ[®] 701 MiR is a thermally stable, high resolution photo resist optimized for dry etching of sub- μm structures.

Sensitivity: g-, h-, and i-line

Developer: aqueous alkaline (KOH-, NaOH-, or TMAH-based)



300 nm structures of AZ[®] 701 MiR

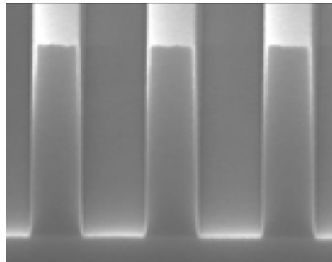


1 μm structure of AZ[®] 701 MiR after 130°C hardbake

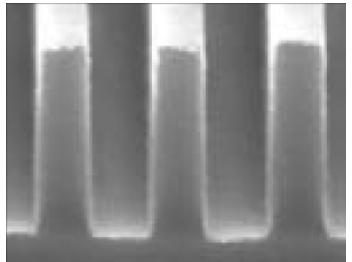
AZ[®] ECI 3000 reveals an improved adhesion as well as a high thermal stability. Therefore, this resist series is well suited for wet- and dry chemical processes. The very high resolution potential allows feature sizes of 300 nm, and yields a bigger and very stable process parameter window towards lower resolution requirements.

Sensitivity: g-, h-, and i-line

Developer: aqueous alkaline (KOH-, NaOH-, or TMAH-based)



900 nm structures of AZ[®] ECI 3027



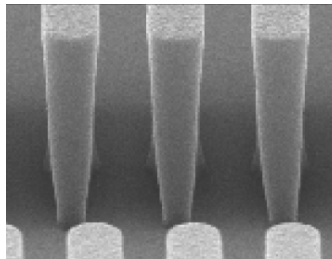
450 nm structures of AZ[®] ECI 3012

AZ[®] nLOF 2000 is a series of cross-linking, thermally very stable negative tone resists. Together with the adjustable undercut, the nLOF 2000 is optimized also for critical lift-off processes.

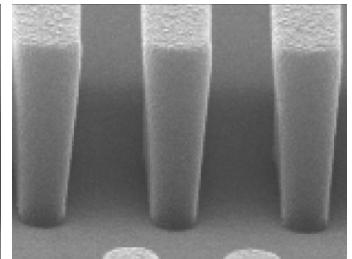
Sensitivity: i-line

Developer: TMAH-based (AZ[®] 326/726/826 MIF)

Lift-off medium / remover: alkaline media or organic solvents



900 nm structures with AZ[®] nLOF 2035



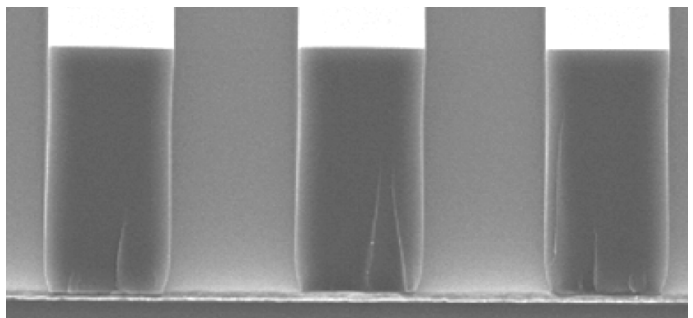
700 nm structures with AZ[®] nLOF 2020

AZ[®] 15 nXT is a cross-linking, Cu-compatible negative resist especially designed for electro plating: Excellent adhesion, no underplating, vertical sidewall profiles, wide compatibility to plating solutions, including Cu, Ni, and Au.

Sensitivity: i-line

Developer: TMAH-based (AZ[®] 326/726/826 MIF)

Remover: Easily strips after plating; stripped completely in AZ[®] Kwik Strip at 70°C for 3 min.



AZ[®] 15 nXT structures (resist film thickness 10 μm)

Interested in further technical information or a free sample? Please contact us:

tech@microchemicals.eu